DB5S308K

Silicon epitaxial planar type

For high speed switching circuits

Features

- Short reverse recovery time t_{rr}
- \bullet Low forward voltage $V_{\rm F}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

Marking Symbol: 3A

Basic Part Number

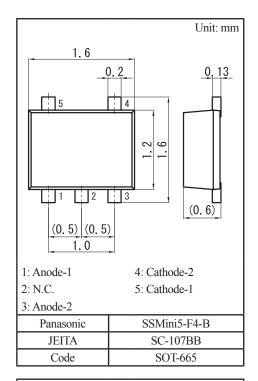
Dual DB2S308 (Parallel)

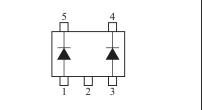
Packaging

DB5S308K0R Embossed type (Thermo-compression sealing): 8 000 pcs / reel (standard)

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage		V _R	30	V
Repetitive peak reverse voltage		V _{RRM}	30	V
Forward current (Average)	Single	T	100	mA
	Double *1	I _{F(AV)}	75	mA
Peak forward current	Single	т	300	mA
	Double *1	- I _{FM}	225	mA
Non-repetitive peak forward surge current *2	Single	т	1	А
	Double *1	- I _{FSM}	0.75	А
Junction temperature		T _j 125		°C
Operating ambient temperature		T _{opr}	-40 to +85	°C
Storage temperature		T _{stg}	-55 to +125	°C





Note) *1: Value of each diode in double diodes used.

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

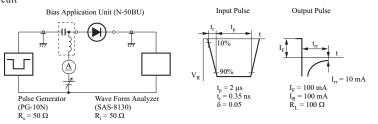
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 10 \text{ mA}$			0.29	v
	V _{F2}	$I_F = 100 \text{ mA}$			0.42	
Reverse current	I _{R1}	$V_R = 10 V$			25	μΑ
	I _{R2}	$V_R = 30 V$			120	
Terminal capacitance	Ct	$V_{R} = 10 V, f = 1 MHz$		2.9		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		1.3		ns

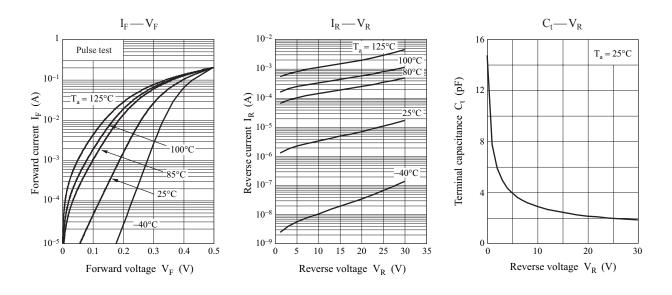
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

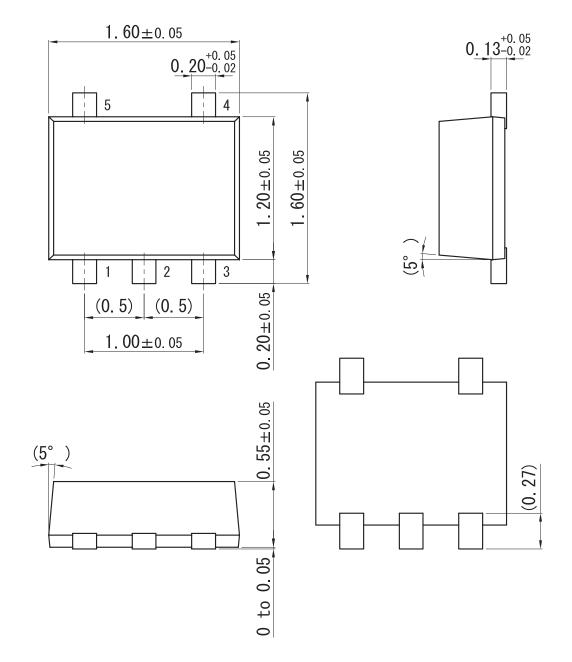
4. *1: t_{rr} measurement circuit



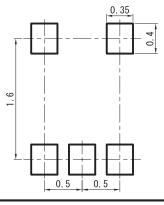


SSMini5-F4-B

Unit: mm



Land Pattern (Reference) (Unit: mm)



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